

Heteroepitaxial cubic SiC layers on silicon.

Material specifications

| Substrate ¹⁾ | Si, SOI | |
|--|--|---|
| Orientation | (100) | (111) |
| Substrate diameter | 100mm | 100mm |
| Other substrate properties (thickness, resistivity, miscut ...) | | |
| Layer | 3C-SiC | |
| Orientation | (100) | (111) |
| Thickness range ²⁾ | 0 – 20µm | 0 – 1µm; Cracks >1µm |
| Thickness variation ²⁾ (%/mean) | $\leq 10\%$ | |
| Electrical conductivity | n type | |
| Unintentional doping ³⁾ ($N_D - N_A$) | $\leq 1 \times 10^{16} \text{ cm}^{-3}$ | |
| Al incorporation ⁴⁾ | $\leq 1 \times 10^{15} \text{ cm}^{-3}$ | |
| Voluntary doping | Nitrogen | |
| Doping range ³⁾⁴⁾ | $1 \times 10^{16} - 1 \times 10^{19} \text{ cm}^{-3}$ | $5 \times 10^{16} - 5 \times 10^{18} \text{ cm}^{-3}$ |
| Doping variation ³⁾⁴⁾ (%/mean) | $\leq 50\%$ | |
| Protrusion density ⁵⁾ | $\leq 3 \times 10^3 \text{ cm}^{-2}$ | |
| Other services – on client's request | | |
| Epiwafer polishing | Frontside: 1Å<RMS roughness <10Å ⁶⁾ . Backside: Optical. | |
| Detailed report on the layer properties | FTIR, XRD, SEM and AFM results ⁷⁾ | |



- 1) If necessary, wafers may be supplied by NOVASIC
- 2) Detailed thickness profile obtained by FTIR spectrometry
- 3) Carrier concentration calculated from C-V measurements
- 4) Dopant incorporation deduced from SIMS measurements
- 5) Microscopic inspection of crystallites or other macro-defects
- 6) Polishing under development for 100mm (111) oriented epiwafers.
- 7) SEM images on 2" and 3" wafers

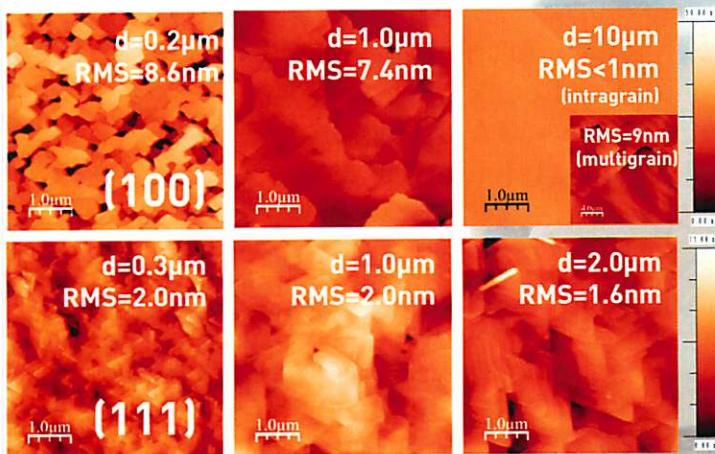
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Polished 3C-SiC layers

Best surface preparation before further processing

As-grown morphology – rough surface

Growth mode (3D islands) is at the origin of rough surfaces of as-grown (100) and (111) oriented 3C-SiC *on-axis* layers.



Polished film – low roughness



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Available services

| | SiC | AlN | GaN | Al ₂ O ₃ | ZnO | Ge, CdTe, SiGe silica.... |
|---------------|-----|-----|-----|--------------------------------|-----|------------------------------|
| Polishing | X | X | X | X | X | X |
| Reclaim | X | X | X | X | X | X |
| Thinning | X | | | | | |
| Planarization | X | X | X | | | |
| Epitaxy | X | | | | | |

Surface quality

| face | SiC | | | | | | | Other materials | | | | | | | |
|---------|------------------------------------|-------|------------------------------------|-------|-----------------------------|-------|-------|-----------------|--|-------|-----|-----|---------------------------------------|----------------------------|--|
| | 4HN - 4HSI On-axis to 8° off | | 6HN - 6HSI On axis to 8° off | | 4H - 6H a- & m- plane | | 3C | | Al ₂ O ₃ c- & r- plane | ZnO | | AlN | | GaN c- a - & m-plane | |
| | Si | C | Si | C | N/A | (100) | (111) | N/A | Zn | O | Al | N | Ga | N | |
| RMS (Å) | < 1 * | < 1 * | < 1 * | < 1 * | < 1 * | < 2 * | < 7 | < 2 * | < 1 * | < 1 * | < 3 | - | < 2 Depending on orientation | 1 | |

* : with atomic steps

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Please feel free to contact us for any further information you may need.

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